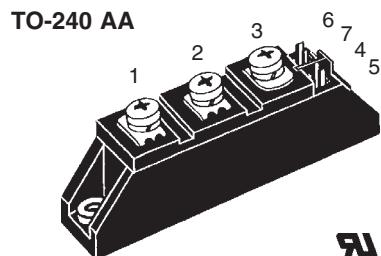


Thyristor Modules

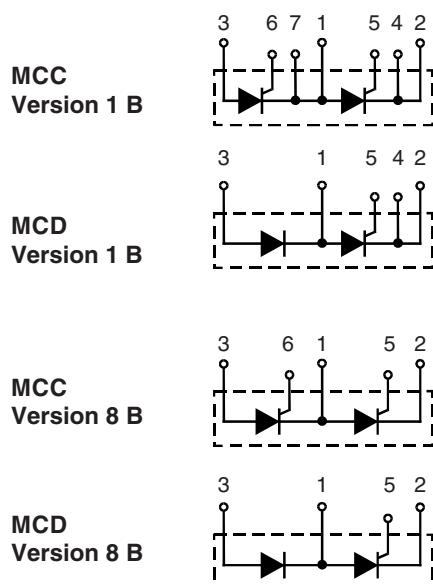
Thyristor/Diode Modules

I_{TRMS} = 2x80 A
I_{TAVM} = 2x51 A
V_{RRM} = 800-1800 V

V _{RSM}	V _{RRM}	Type					
V _{DSM}	V _{DRM}		1 B	8 B	Version	1 B	8 B
900	800	MCC 44-08	io1 B / io8 B		MCD 44-08	io1 B / io8 B	
1300	1200	MCC 44-12	io1 B / io8 B		MCD 44-12	io1 B / io8 B	
1500	1400	MCC 44-14	io1 B / io8 B		MCD 44-14	io1 B / io8 B	
1700	1600	MCC 44-16	io1 B / io8 B		MCD 44-16	io1 B / io8 B	
1900	1800	MCC 44-18	io1 B / io8 B		MCD 44-18	io1 B / io8 B	



Symbol	Conditions	Maximum Ratings		
I _{TRMS} , I _{FRMS}	T _{VJ} = T _{VJM}	80	A	
I _{TAVM} , I _{FAVM}	T _C = 83°C; 180° sine	51	A	
	T _C = 85°C; 180° sine	49	A	
I _{TSM} , I _{FSM}	T _{VJ} = 45°C; V _R = 0;	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	1150	A
	T _{VJ} = T _{VJM} ; t = 10 ms; V _R = 0;	(50 Hz), sine t = 8.3 ms (60 Hz), sine	1230	A
I ² dt	T _{VJ} = 45°C; V _R = 0,	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	6600	A ² s
	T _{VJ} = T _{VJM} ; V _R = 0;	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	6280	A ² s
(di/dt) _{cr}	T _{VJ} = T _{VJM} ; f = 50Hz; t _p = 200μs; V _D = 2/3 V _{DRM} ; I _G = 0.45 A; di _G /dt = 0.45 A/μs	repetitive, I _T = 150 A non repetitive, I _T = I _{TAVM}	150	A/μs
(dv/dt) _{cr}	T _{VJ} = T _{VJM} ; R _{GR} = ∞; method 1 (linear voltage rise)	V _{DR} = 2/3 V _{DRM}	1000	V/μs
P _{GM}	T _{VJ} = T _{VJM} ; I _T = I _{TAVM} ;	t _p = 30 μs t _p = 300 μs	10 5	W
P _{GAV}			0.5	W
V _{RGM}			10	V
T _{VJ}			-40...+125	°C
T _{VJM}			125	°C
T _{stg}			-40...+125	°C
V _{ISOL}	50/60 Hz, RMS; I _{ISOL} ≤ 1 mA;	t = 1 min t = 1 s	3000 3600	V~ V~
M _d	Mounting torque (M5) Terminal connection torque (M5)		2.5-4.0/22-35 Nm/lb.in. 2.5-4.0/22-35 Nm/lb.in.	
Weight	typical including screws		90	g



Features

- International standard package, JEDEC TO-240 AA
- Direct copper bonded Al₂O₃-ceramic base plate
- Planar passivated chips
- Isolation voltage 3600 V~
- UL registered, E 72873
- Gate-cathode twin pins for version 1B

Applications

- DC motor control
- Softstart AC motor controller
- Light, heat and temperature control

Advantages

- Space and weight savings
- Simple mounting with two screws
- Improved temperature and power cycling
- Reduced protection circuits

Symbol	Conditions	Characteristic Values	
I_{RRM}, I_{DRM}	$T_{VJ} = T_{VJM}; V_R = V_{RRM}; V_D = V_{DRM}$	5	mA
V_T, V_F	$I_T, I_F = 200 \text{ A}; T_{VJ} = 25^\circ\text{C}$	1.75	V
V_{T0}	For power-loss calculations only ($T_{VJ} = 125^\circ\text{C}$)	0.85	V
r_T		5.3	$\text{m}\Omega$
V_{GT}	$V_D = 6 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$	1.5	V
I_{GT}	$V_D = 6 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$	100	mA
V_{GD}	$T_{VJ} = T_{VJM}; V_D = 2/3 V_{DRM}$	0.2	V
I_{GD}		10	mA
I_L	$T_{VJ} = 25^\circ\text{C}; t_p = 10 \mu\text{s}, V_D = 6 \text{ V}$ $I_G = 0.45 \text{ A}; di_d/dt = 0.45 \text{ A}/\mu\text{s}$	450	mA
I_H	$T_{VJ} = 25^\circ\text{C}; V_D = 6 \text{ V}; R_{GK} = \infty$	200	mA
t_{gd}	$T_{VJ} = 25^\circ\text{C}; V_D = 1/2 V_{DRM}$ $I_G = 0.45 \text{ A}; di_d/dt = 0.45 \text{ A}/\mu\text{s}$	2	μs
t_q	$T_{VJ} = T_{VJM}; I_T = 120 \text{ A}, t_p = 200 \mu\text{s}; -di/dt = 10 \text{ A}/\mu\text{s}$ $V_R = 100 \text{ V}; dv/dt = 20 \text{ V}/\mu\text{s}; V_D = 2/3 V_{DRM}$	typ. 150	μs
Q_s	$T_{VJ} = T_{VJM}; I_T/I_F = 50 \text{ A}, -di/dt = 0.64 \text{ A}/\mu\text{s}$	90	μC
I_{RM}		11	A
R_{thJC}	per thyristor/diode; DC current	0.53	K/W
	per module	0.265	K/W
R_{thJK}	per thyristor/diode; DC current	0.73	K/W
	per module	0.365	K/W
d_s	Creepage distance on surface	12.7	mm
d_A	Strike distance through air	9.6	mm
a	Maximum allowable acceleration	50	m/s^2

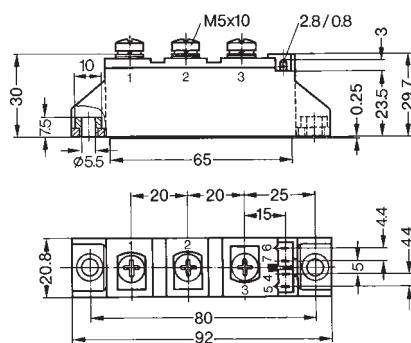
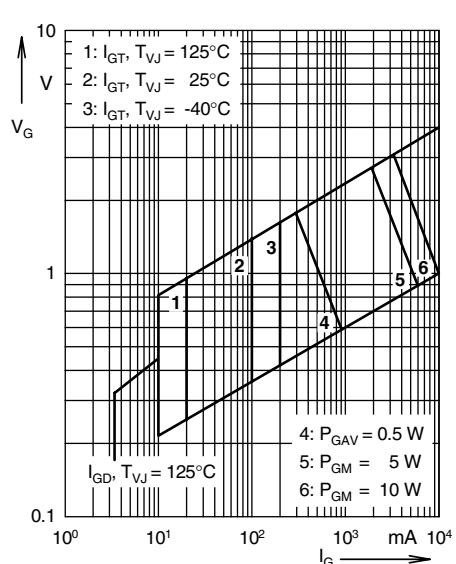
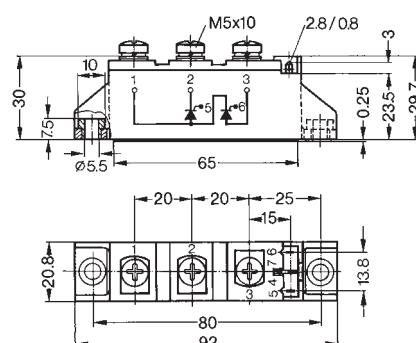
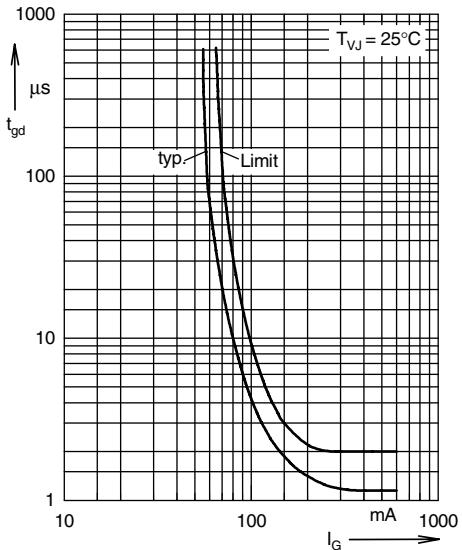
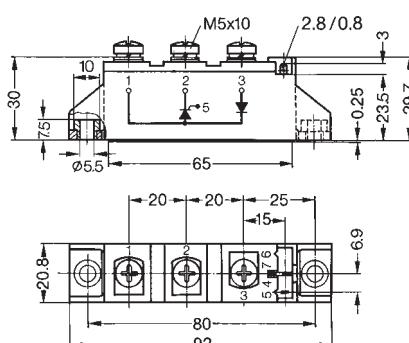
Optional accessories for module-type MCC 44 version 1 B

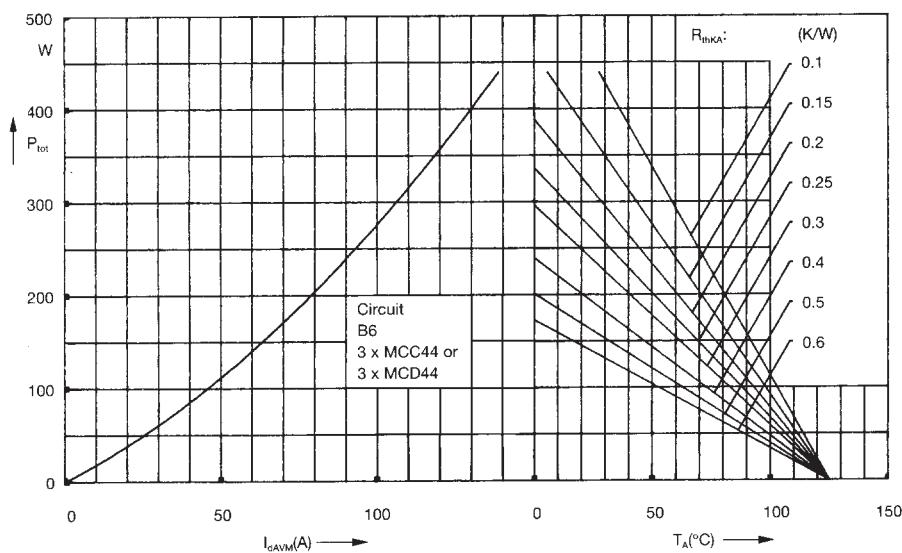
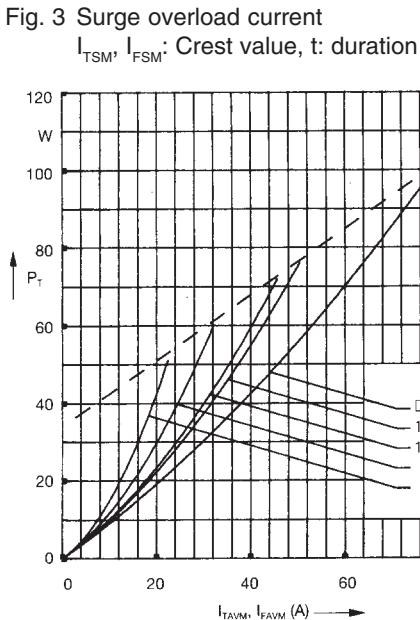
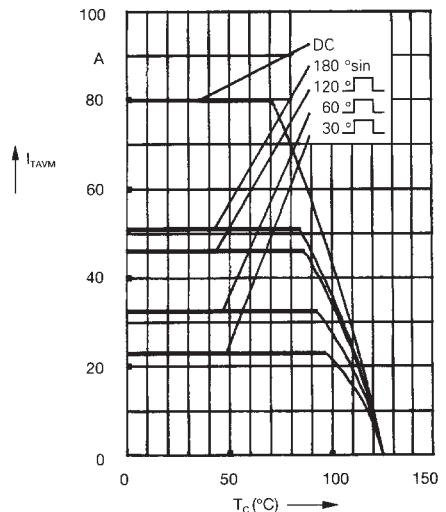
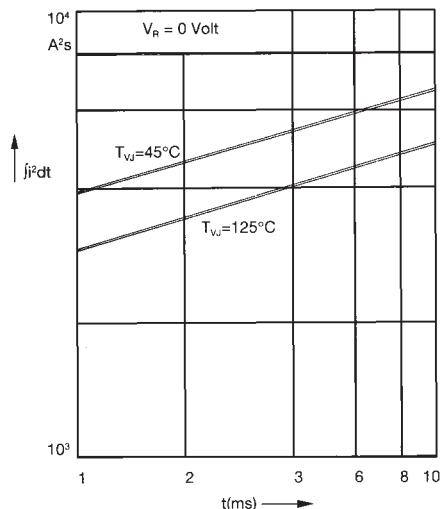
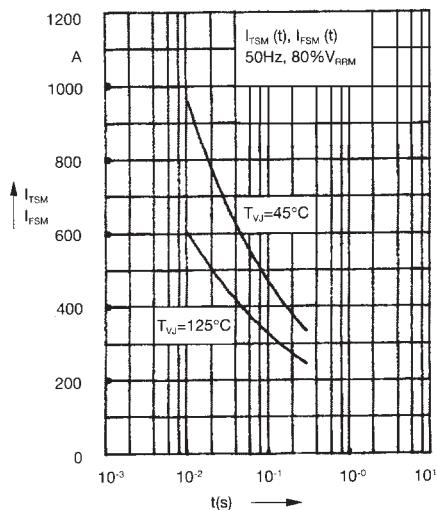
Keyed gate/cathode twin plugs with wire length = 350 mm, gate = yellow, cathode = red

Type ZY 200L (L = Left for pin pair 4/5) } UL 758, style 1385,

Type ZY 200R (R = right for pin pair 6/7) } CSA class 5851, guide 460-1-1

Dimensions in mm (1 mm = 0.0394")

MCC/MCD Version 1 B

MCC Version 8 B

Fig. 1 Gate trigger characteristics

Fig. 2 Gate trigger delay time
MCD Version 8 B




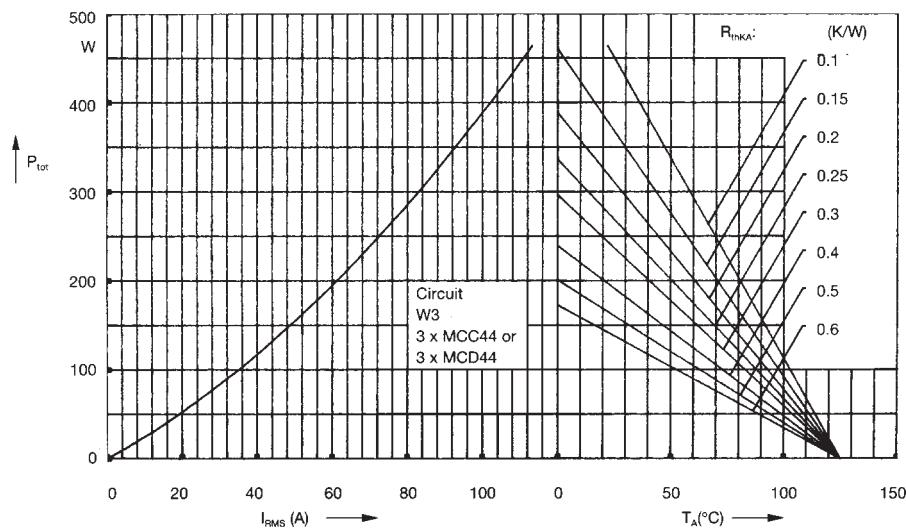


Fig. 7 Three phase AC-controller:
Power dissipation versus RMS output current and ambient temperature

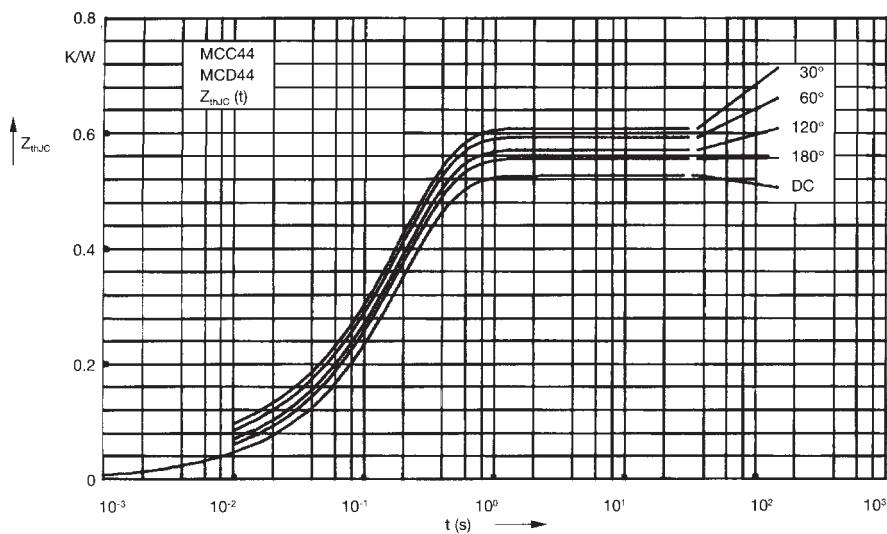


Fig. 8 Transient thermal impedance junction to case (per thyristor or diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.53
180°	0.55
120°	0.58
60°	0.6
30°	0.62

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.015	0.0035
2	0.026	0.02
3	0.489	0.195

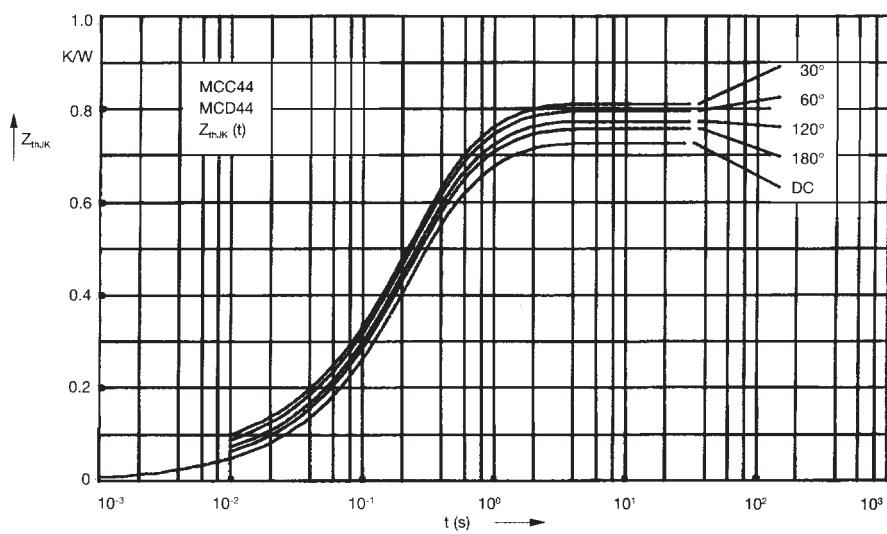


Fig. 9 Transient thermal impedance junction to heatsink (per thyristor or diode)

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.73
180°	0.75
120°	0.78
60°	0.8
30°	0.82

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.015	0.0035
2	0.026	0.02
3	0.489	0.195
4	0.2	0.68